

#### MOS FIELD EFFECT TRANSISTOR

### NP80N055CHE, NP80N055DHE, NP80N055EHE

## SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

#### **DESCRIPTION**

This product is N-channel MOS Field Effect Transistor designed for high current switching applications.

#### **FEATURES**

- Channel temperature 175 degree rated
- Super low on-state resistance
- $\bigstar$  RDS(on) = 11 m $\Omega$  MAX. (VGS = 10 V, ID = 40 A)
- ★ Low Ciss : Ciss = 2400 pF TYP.
  - Built-in gate protection diode

#### **ORDERING INFORMATION**

PART NUMBER	PACKAGE		
NP80N055CHE	TO-220AB(MP-25)		
NP80N055DHE	TO-262(MP-25 Fin Cut)		
NP80N055EHE	TO-263(MP-25ZJ)		

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

	Drain to Source Voltage	VDSS	55	V
	Gate to Source Voltage	Vgss	±20	V
	Drain Current (DC) Note1	ID(DC)	±80	Α
	Drain Current (Pulse) Note2	D(pulse)	±320	Α
	Total Power Dissipation (T <sub>A</sub> = 25°C)	Pτ	1.8	W
*	Total Power Dissipation (Tc = 25°C)	Pτ	120	W
*	Single Avalanche Current	las	45 / 31 / 10	Α
*	Single Avalanche Energy Note3	Eas	2.0 / 96 / 100	mJ
	Channel Temperature	Tch	175	°C
	Storage Temperature	Tstg	-55 to +175	°C

**Notes 1.** Package Limit =  $\pm$  75 A

- **2.** PW  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1 %
- 3. Starting T<sub>ch</sub> = 25°C, R<sub>G</sub> = 25  $\Omega$  , V<sub>GS</sub> = 20 V $\rightarrow$ 0 V

#### THERMAL RESISTANCE

*	Channel to Case	Rth(ch-C)	1.25	°C/W
	Channel to Ambient	Rth(ch-A)	83.3	°C/W

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

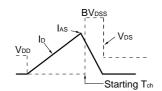


#### **★ ELECTRICAL CHARACTERISTICS (TA = 25 °C)**

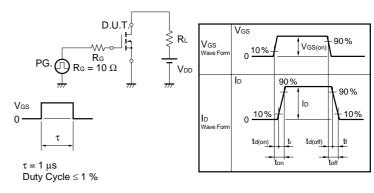
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	R <sub>DS(on)</sub>	Vgs = 10 V, ID = 40 A		8.2	11	mΩ
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	2.0	3.0	4.0	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 40 A	15	30		S
Drain Leakage Current	IDSS	V <sub>DS</sub> = 55 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate to Source Leakage Current	Igss	V <sub>G</sub> S = ±20 V, V <sub>D</sub> S = 0 V			±10	μΑ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		2400	3600	pF
Output Capacitance	Coss			380	570	pF
Reverse Transfer Capacitance	Crss			180	330	pF
Turn-on Delay Time	td(on)	ID = 40 A, VGS(on) = 10 V, VDD = 28 V,		100	220	ns
Rise Time	tr	R <sub>G</sub> = 10 Ω		1500	3750	ns
Turn-off Delay Time	td(off)			155	310	ns
Fall Time	tf			300	750	ns
Total Gate Charge	Q <sub>G</sub>	ID = 80 A, VDD = 44 V, VGS = 10 V		40	60	nC
Gate to Source Charge	Qgs			12		nC
Gate to Drain Charge	Q <sub>GD</sub>			16		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	IF = 80 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 80A, Vgs = 0 V, di/dt = $100A/\mu s$		49		ns
Reverse Recovery Charge	Qrr			90		nC

#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c} \text{D.U.T.} \\ \text{Rg} = 25 \ \Omega \\ \text{VGS} = 20 \rightarrow 0 \ V \end{array} \begin{array}{c} \text{PG.} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \end{array} \begin{array}{c} \text{$\downarrow$} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \end{array} \begin{array}{c} \text{Vob} \\ \text{$\downarrow$} \end{array}$



#### **TEST CIRCUIT 2 SWITCHING TIME**



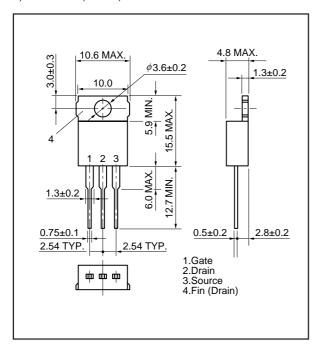
#### **TEST CIRCUIT 3 GATE CHARGE**

$$\begin{array}{c|c} D.U.T. \\ \hline I_G = 2 \text{ mA} \\ \hline \hline W & D.U.T. \\ \hline \\ PG. \\ \hline \end{array} \begin{array}{c} R_L \\ \hline \\ V_{DD} \\ \hline \end{array}$$

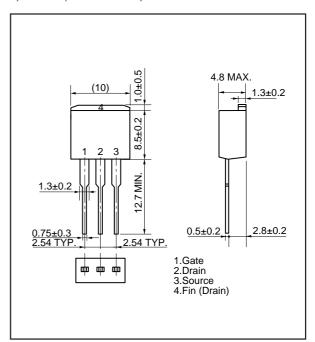


#### PACKAGE DRAWINGS (Unit: mm)

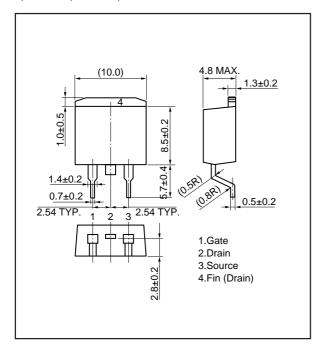
#### 1) TO-220AB (MP-25)



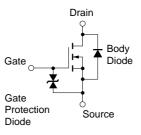
#### 2) TO-262 (MP-25 Fin Cut)



#### 3) TO-263 (MP-25ZJ)



#### **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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